NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL–C–26074, CLASS 1,
   100 TO 300 MICRONICHES (2.5um – 7.6um) THICK.
   GOLD PLATE PER MIL–G–45204, TYPE 3, GRADE A, CLASS 1
   (40 TO 80 MICRONICHES (1um – 2um) THICK).
   BODY SURFACE FINISH: VDI 21–24 (1.12–1.6 Ro).

3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO–220.

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